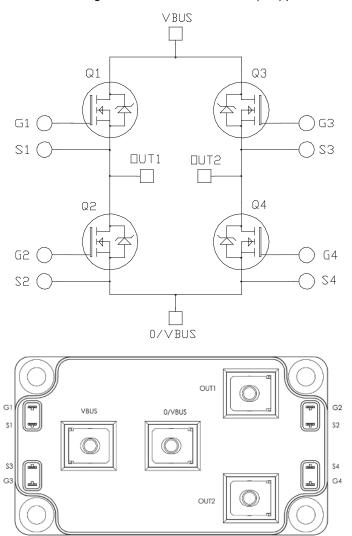
# MSCSM70HM05AG

# **Full Bridge SiC Power Module**

### **Product Overview**

The MSCSM70HM05AG device is a full bridge 700V, 349A silicon carbide (SiC) power module.



**Note:** All ratings at  $T_J$  = 25 °C, unless otherwise specified.

**⚠** CAUTION

These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

### **Features**

The following are key features of the MSCSM70HM05AG device:

- SiC Power MOSFET
  - Low R<sub>DS(on)</sub>
  - High temperature performance
- Kelvin source for easy drive
- Low stray inductance
- M5 power connectors
- Aluminum Nitride (AIN) substrate for improved thermal performance

### **Benefits**

The following are the benefits of MSCSM70HM05AG device:

- High efficiency converter
- Outstanding performance at high frequency operation
- Stable temperature behavior
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- RoHS compliant

### **Application**

The MSCSM70HM05AG device is designed for the following applications:

- Welding converters
- Switched mode power supplies
- Uninterruptible power supplies
- EV motor and traction drive

### 1. Electrical Specifications

This section provides the electrical specifications of the MSCSM70HM05AG device.

### 1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings per SiC MOSFET of the MSCSM70HM05AG device.

**Table 1-1. Absolute Maximum Ratings** 

Symbol	Parameter		Maximum Ratings	Unit	
V <sub>DSS</sub>	Drain-Source voltage	Source voltage 7		V	
I <sub>D</sub>	Continuous drain current	ous drain current $T_C = 25 ^{\circ}C$ 3		А	
		T <sub>C</sub> = 80 °C	278		
I <sub>DM</sub>	Pulsed drain current	drain current			
V <sub>GS</sub>	Gate-Source voltage		-10/23	V	
R <sub>DS(on)</sub>	Drain-Source ON resistance	ce ON resistance		mΩ	
P <sub>D</sub>	Power dissipation	T <sub>C</sub> = 25 °C	966	W	

The following table lists the electrical characteristics per SiC MOSFET of the MSCSM70HM05AG device.

**Table 1-2. Electrical Characteristics** 

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>DSS</sub>	Zero gate voltage drain current	V <sub>GS</sub> = 0V V <sub>DS</sub> = 700V		_	_	300	μΑ
R <sub>DS(on)</sub>	Drain-Source on	V <sub>GS</sub> = 20V	T <sub>J</sub> = 25 °C	_	5	6.4	mΩ
	resistance	I <sub>D</sub> = 120A	T <sub>J</sub> = 175 °C	_	6.3	_	
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>GS</sub> = V <sub>DS</sub> I <sub>D</sub> = 12 mA		1.9	2.4	_	V
I <sub>GSS</sub>	Gate–Source leakage current	$V_{GS} = 20V; V_{DS} = 0$	V <sub>GS</sub> = 20V; V <sub>DS</sub> = 0V		_	300	nA

The following table lists the dynamic characteristics per SiC MOSFET of the MSCSM70HM05AG device.

**Table 1-3. Dynamic Characteristics** 

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>GS</sub> = 0V		_	13.5	_	nF
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 700V	os = 700V	_	1.5	_	
C <sub>rss</sub>	Reverse transfer capacitance	f = 1 MHz		_	0.09	_	
Qg	Total gate charge	V <sub>GS</sub> = -5V/20V		_	645	_	nC
Q <sub>gs</sub>	Gate-Source charge	V <sub>Bus</sub> = 470V		_	174	_	
$Q_{gd}$	Gate-Drain charge	I <sub>D</sub> = 120A		_	105	_	
T <sub>d(on)</sub>	Turn-on delay time	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150 °C	_	78	_	ns
Tr	Rise time	V <sub>Bus</sub> = 400V		_	125	_	
T <sub>d(off)</sub>	Turn-off delay time	I <sub>D</sub> = 240A		_	214	_	
T <sub>f</sub>	Fall time	$R_{G(on)} = 24\Omega$ $R_{G(off)} = 5.4\Omega$			92	_	
Eon	Turn-on energy	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150 °C	_	5	_	mJ
E <sub>off</sub>	Turn-off energy	$V_{Bus}$ = 400V $I_{D}$ = 240A $R_{G(on)}$ = 24 $\Omega$ $R_{G(off)}$ = 5.4 $\Omega$		_	5.3	_	
R <sub>Gint</sub>	Internal gate resistance	,		_	1.9	_	Ω
R <sub>thJC</sub>	Junction-to-case thermal res	unction-to-case thermal resistance		_	_	0.155	°C/W

The following table lists the body diode ratings and characteristics per SiC MOSFET of the MSCSM70HM05AG device.

**Table 1-4. Body Diode Ratings and Characteristics** 

Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub>	Diode forward voltage	V <sub>GS</sub> = 0V; I <sub>SD</sub> = 120A	_	3.4	_	V
		$V_{GS} = -5V$ ; $I_{SD} = 120A$	_	3.8	_	
t <sub>rr</sub>	Reverse recovery time	$I_{SD} = 120A; V_{GS} = -5V$	_	40	_	ns
Q <sub>rr</sub>	Reverse recovery charge	$V_R = 400V$ ; $di_F/dt = 3000 A/\mu s$	_	1.5	_	μC
Irr	Reverse recovery current		_	57	_	Α

### 1.2 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCSM70HM05AG device.

Table 1-5. Thermal and Package Characteristics

Symbol	Characteristics	Characteristics			Max.	Unit
V <sub>ISOL</sub>	RMS isolation voltage, any term	ninal to case t = 1 m	in, 50 Hz/60 Hz	4000	_	V
T <sub>J</sub>	Operating junction temperature range			-40	175	°C
T <sub>JOP</sub>	Recommended junction temper	ature under switchir	ng conditions	-40	T <sub>Jmax</sub> –25	
T <sub>STG</sub>	Storage temperature range	Storage temperature range			125	
T <sub>C</sub>	Operating case temperature	Operating case temperature		-40	125	
Torque	ue Mounting torque To hea		M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	/t Package weight			_	300	g

### 1.3 Typical SiC MOSFET Performance Curve

This section shows the typical SiC MOSFET performance curves of the MSCSM70HM05AG device.

Figure 1-1. Maximum Thermal Impedance

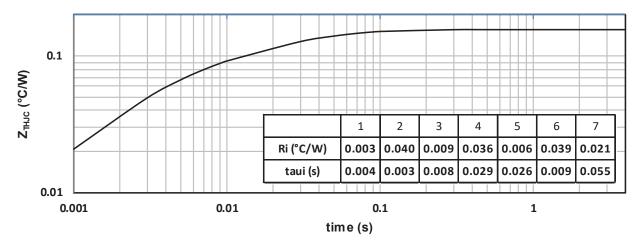


Figure 1-2. Output Characteristics,  $T_J = 25$  °C

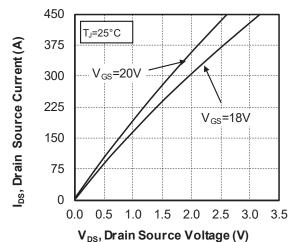


Figure 1-3. Output Characteristics, T<sub>J</sub> = 175 °C

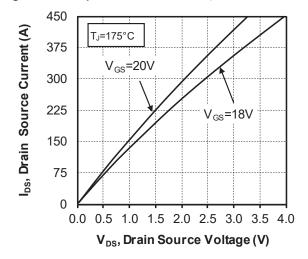


Figure 1-4. Normalized R<sub>DS(on)</sub> vs. Temperature

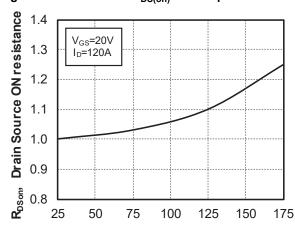


Figure 1-5. Transfer Characteristics

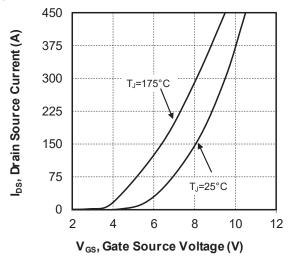


Figure 1-6. Switching Energy vs. Current

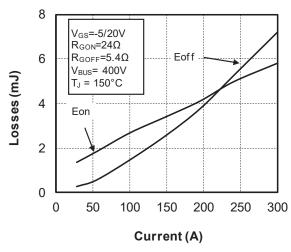


Figure 1-7. Turn On Energy vs. Rg

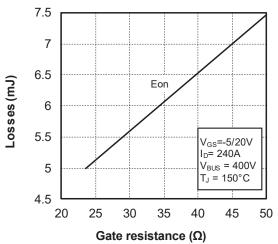


Figure 1-8. Capacitance vs. Drain Source Voltage

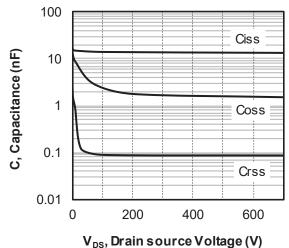


Figure 1-9. Gate Charge vs. Gate Source Voltage

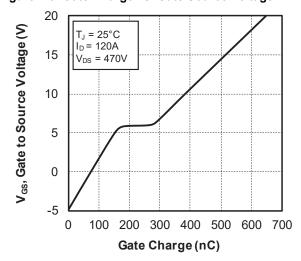


Figure 1-10. Body Diode Characteristics, T<sub>J</sub> = 25 °C

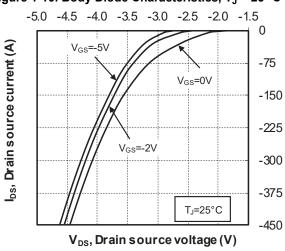


Figure 1-11. 3<sup>rd</sup> Quadrant Characteristics, T<sub>J</sub> = 25 °C

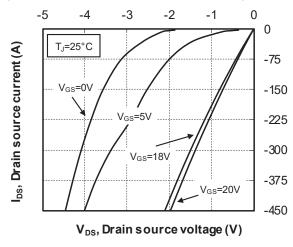
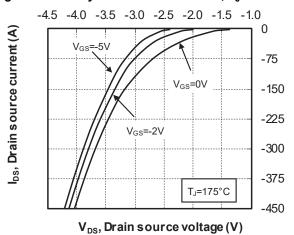


Figure 1-12. Body Diode Characteristics, T<sub>J</sub> = 175 °C Figure 1-13. 3<sup>rd</sup> Quadrant Characteristics, T<sub>J</sub> = 175 °C



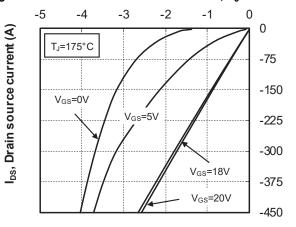


Figure 1-14. Operating Frequency vs Drain Current

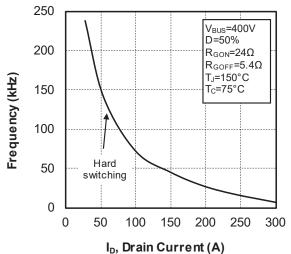
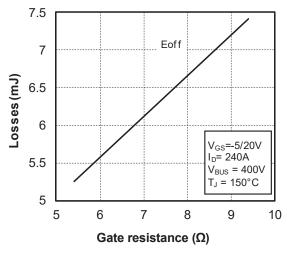


Figure 1-15. Turn Off Energy vs. Rg



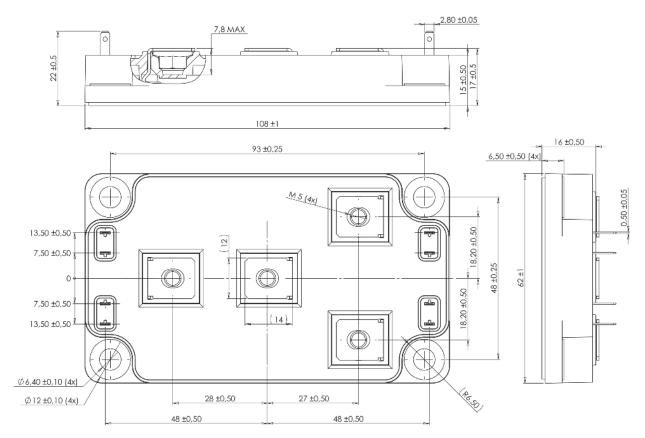
## 2. Package Specifications

The following section shows the package specification of the MSCSM70HM05AG device.

### 2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM70HM05AG device. The dimensions in the following figure are in millimeters.

Figure 2-1. Package Outline Drawing



Note: See APT0601—Mounting Instructions for SP6 Power Modules for more information.

## MSCSM70HM05AG

**Revision History** 

## 3. Revision History

Revision	Date	Description
A	06/2022	Initial Release

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